

APPARATUS FOR SEMICONDUCTOR CHIP ASSEMBLY

ABSTRACT

5 The present invention relates to an apparatus for semiconductor chip assembly and in particular, but not exclusively, to a nozzle apparatus and a method for bonding a semiconductor chip to a mounting surface of a semiconductor device. The nozzle apparatus comprises a body for holding an adhesive material, a nozzle head and a plurality of nozzles attached to the tip
10 of the nozzle head. The plurality of nozzles is arranged in various patterns for bonding or adhering different sizes of the semiconductor chip to the mounting surface such that voids are prevented from remaining in the adhesive material after the chip has been pressed against the mounting surface.

15 **FIG. 2B**